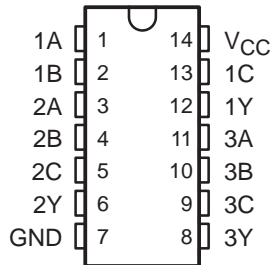


# SN54ACT10, SN74ACT10 TRIPLE 3-INPUT POSITIVE-NAND GATES

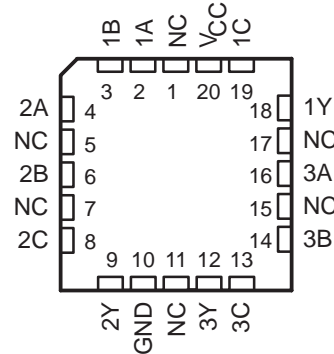
SCAS526C – AUGUST 1995 – REVISED OCTOBER 2003

- 4.5-V to 5.5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 9.5 ns at 5 V
- Inputs Are TTL-Voltage Compatible

SN54ACT10 . . . J OR W PACKAGE  
SN74ACT10 . . . D, DB, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54ACT10 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

The 'ACT10 devices contain three independent 3-input NAND gates. The devices perform the Boolean functions  $Y = \overline{A \cdot B \cdot C}$  or  $Y = \overline{A} + \overline{B} + \overline{C}$  in positive logic.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74ACT10N	SN74ACT10N
		SOIC – D	Tube	SN74ACT10D
		Tape and reel	SN74ACT10DR	
	SOP – NS	Tape and reel	SN74ACT10NSR	ACT10
	SSOP – DB	Tape and reel	SN74ACT10DBR	AD10
	TSSOP – PW	Tube	SN74ACT10PW	AD10
Tape and reel		SN74ACT10PWR		
–55°C to 125°C	CDIP – J	Tube	SNJ54ACT10J	SNJ54ACT10J
	CFP – W	Tube	SNJ54ACT10W	SNJ54ACT10W
	LCCC – FK	Tube	SNJ54ACT10FK	SNJ54ACT10FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

FUNCTION TABLE  
(each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	L
L	X	X	H
X	L	X	H
X	X	L	H



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

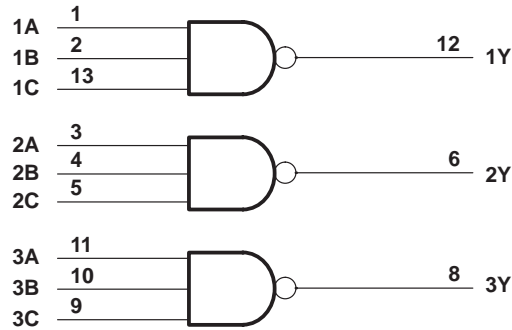
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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54ACT10, SN74ACT10 TRIPLE 3-INPUT POSITIVE-NAND GATES

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## logic diagram, each gate (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 200$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
D package .....	86°C/W
DB package .....	96°C/W
N package .....	80°C/W
NS package .....	76°C/W
PW package .....	113°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

	SN54ACT10		SN74ACT10		UNIT
	MIN	MAX	MIN	MAX	
$V_{CC}$ Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$ High-level input voltage	2		2		V
$V_{IL}$ Low-level input voltage		0.8		0.8	V
$V_I$ Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$V_O$ Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$ High-level output current		-24		-24	mA
$I_{OL}$ Low-level output current		24		24	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		8		8	ns/V
$T_A$ Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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# SN54ACT10, SN74ACT10 TRIPLE 3-INPUT POSITIVE-NAND GATES

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54ACT10		SN74ACT10		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.49		4.4		4.4	V	
		5.5 V	5.4	5.49		5.4		5.4		
	I <sub>OH</sub> = -24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I <sub>OH</sub> = -50 mA†	5.5 V				3.85				
I <sub>OH</sub> = -75 mA†	5.5 V						3.85			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	4.5 V	0.001	0.1		0.1		0.1	V	
		5.5 V	0.001	0.1		0.1		0.1		
	I <sub>OL</sub> = 24 mA	4.5 V	0.36			0.5		0.44		
		5.5 V	0.36			0.5		0.44		
	I <sub>OL</sub> = 50 mA†	5.5 V				1.65				
I <sub>OL</sub> = 75 mA†	5.5 V						1.65			
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V	±0.1			±1		±1	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V	4			80		40	μA	
ΔI <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V	0.6			1.6		1.5	mA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V	2.6						pF	

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			SN54ACT10		SN74ACT10		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	Any	Y	1	6.5	9	1	10	1	10	ns
t <sub>PHL</sub>			1	6.5	9	1	9.5	1	9.5	

operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	C <sub>L</sub> = 50 pF, f = 1 MHz	25	pF

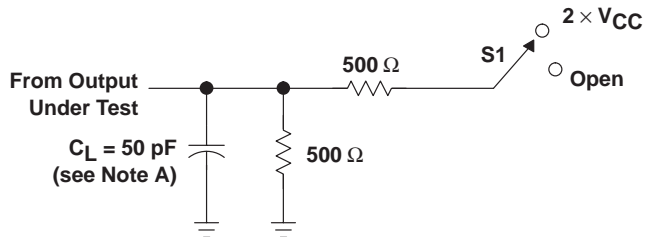


# SN54ACT10, SN74ACT10 TRIPLE 3-INPUT POSITIVE-NAND GATES

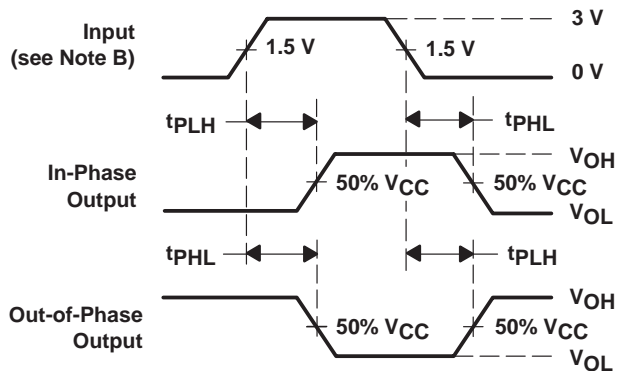
SCAS526C – AUGUST 1995 – REVISED OCTOBER 2003

## PARAMETER MEASUREMENT INFORMATION

TEST	S1
$t_{PLH}/t_{PHL}$	Open



LOAD CIRCUIT



VOLTAGE WAVEFORMS

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9218201M2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9218201M2A SNJ54ACT 10FK	<a href="#">Samples</a>
5962-9218201MCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9218201MC A SNJ54ACT10J	<a href="#">Samples</a>
5962-9218201MDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9218201MD A SNJ54ACT10W	<a href="#">Samples</a>
SN74ACT10DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD10	<a href="#">Samples</a>
SN74ACT10DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT10	<a href="#">Samples</a>
SN74ACT10DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT10	<a href="#">Samples</a>
SN74ACT10N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ACT10N	<a href="#">Samples</a>
SN74ACT10PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD10	<a href="#">Samples</a>
SNJ54ACT10FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9218201M2A SNJ54ACT 10FK	<a href="#">Samples</a>
SNJ54ACT10J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9218201MC A SNJ54ACT10J	<a href="#">Samples</a>
SNJ54ACT10W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9218201MD A SNJ54ACT10W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54ACT10, SN74ACT10 :**

- Catalog : [SN74ACT10](#)
  
- Automotive : [SN74ACT10-Q1](#), [SN74ACT10-Q1](#)
  
- Military : [SN54ACT10](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
  
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT10DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74ACT10DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT10PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT10DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74ACT10DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ACT10PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9218201M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9218201MDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74ACT10N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ACT10N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54ACT10FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ACT10W	W	CFP	14	25	506.98	26.16	6220	NA

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/G 08/15

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



4040180-2/F 04/14

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14

# DB0014A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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